

THIN SEMICONDUCTOR DIE PACKAGES AND ASSOCIATED SYSTEMS
AND METHODS

ABSTRACT

Thin semiconductor die packages and associated systems and methods are disclosed. A package in accordance with a particular embodiment includes a semiconductor die having die bond sites, a conductive structure positioned proximate to the semiconductor die and having first bond sites and second bond sites spaced apart from the first bond sites, and conductive couplers connected between the first bond sites of the conductive structure and the die bond sites of the semiconductor die. A cover can be positioned adjacent to the semiconductor die, and can include a recess in which the conductive couplers are received.

Fig. 2